

IN THE CLAIMS

Please amend the Claims as follows:

- 1) (currently amended) A method of manufacturing a semiconductor device comprising:
 - a) depositing a first oxide layer over a periphery transistor comprising a gate stack, a drain side sidewall and a source side sidewall and over a core transistor comprising a gate stack, a source side sidewall and a drain side sidewall;
 - b) etching said first oxide layer wherein a portion of said first oxide layer remains on said source side sidewall and on said drain side sidewall of said periphery transistor and on said source side sidewall and on said drain side sidewall of said core transistor;
 - c) etching said first oxide layer from said source side sidewall of said core transistor while preserving said first layer on said drain side sidewall of said core transistor;
 - d) depositing a second oxide layer over said periphery transistor and said core transistor; and
 - e) etching said second oxide layer wherein a portion of said second oxide layer remains on said first oxide layer formed on said source side sidewall and on said drain side sidewall of said periphery transistor and wherein

said second ~~oxide~~ layer remains on said source side sidewall and on said drain side sidewall of said core transistor.

2) (currently amended) The method as described in Claim 1 wherein said first ~~oxide~~ layer is silicon nitride.

3) (currently amended) The method as described in Claim 1 wherein said first ~~oxide~~ layer is silicon oxide and silicon nitride.

4) (currently amended) The method as described in Claim 1 wherein said second ~~oxide~~ layer is silicon nitride.

5) (original) The method as described in Claim 1 wherein said b) is a chemical etch, wherein said chemical etch does not remove material from said gate stack of said periphery transistor and does not remove material from said gate stack of said core transistor.

6) (original) The method as described in Claim 1 wherein said c) is a self aligned source etch.

7) (currently amended) The method as described in Claim 1 wherein said first ~~oxide~~ layer is thicker than said second ~~oxide~~ layer.

8) (original) The method as described in Claim 1 wherein said core transistor is a flash memory cell.

9) (currently amended) A method for simultaneously manufacturing a wide sidewall spacer on a periphery transistor and a narrow sidewall spacer on a core transistor comprising:

a) depositing a first ~~oxide~~ layer over a periphery transistor comprising a gate stack, a drain side sidewall and a source side sidewall and over a core transistor comprising a gate stack, a source side sidewall and a drain side sidewall;

b) etching said first ~~oxide~~ layer wherein a portion of said first ~~oxide~~ layer remains on said source side sidewall and on said drain side sidewall of said periphery transistor and on said source side sidewall and said drain side sidewall of said core transistor;

c) masking and etching said ~~oxide~~ first layer from said source side sidewall and while preserving said first layer on said drain sidewall of said core transistor;

d) depositing a second ~~oxide~~ layer over said periphery transistor and said core transistor; and

e) etching said second ~~oxide~~ layer wherein a portion of said second ~~oxide~~ layer remains on said first ~~oxide~~ layer formed on said source side sidewall

and said drain side sidewall of said periphery transistor resulting in a wide sidewall spacer and wherein said second ~~oxide~~ layer remains on said source side sidewall and said drain side sidewall of said core transistor resulting in a narrow sidewall spacer.

10) (currently amended) The method as described in Claim 9 wherein said first ~~oxide~~ layer is silicon nitride.

11) (currently amended) The method as described in Claim 9 wherein said first ~~oxide~~ layer is silicon oxide and silicon nitride.

12) (currently amended) The method as described in Claim 9 wherein said second ~~oxide~~ layer is silicon nitride.

13) (original) The method as described in Claim 9 wherein said b) is a chemical etch, wherein said chemical etch does not remove material from said gate stack of said periphery transistor and does not remove material from said gate stack of said core transistor.

14) (currently amended) The method as described in Claim 9 wherein said first ~~oxide~~ layer is thicker than said second ~~oxide~~ layer.

15) (original) The method as described in Claim 9 wherein said core transistor is a flash memory cell.

16) (currently amended) A method for simultaneously manufacturing a semiconductor comprising a wide sidewall spacer and a narrow sidewall spacer comprising:

a) depositing a first ~~oxide~~ layer over a first transistor comprising a gate stack, a drain side sidewall and a source side sidewall and over a second transistor comprising a gate stack, a source side sidewall and a drain side sidewall;

b) etching said first ~~oxide~~ layer wherein a portion of said first ~~oxide~~ layer remains on said source side sidewall and on said drain side sidewall of said first transistor and on said source side sidewall and on said drain side sidewall of said second transistor;

c) etching said first ~~oxide~~ layer from said source side sidewall of said second transistor while preserving said first layer on said drain sidewall of said second transistor;

d) depositing a second ~~oxide~~ layer over said first transistor and said second transistor; and

e) etching said second ~~oxide~~ layer wherein a portion of said second ~~oxide~~ layer remains on said first ~~oxide~~ layer formed on said source side sidewall and on said drain side sidewall of said first transistor and wherein said

second ~~oxide~~ layer remains on said source side sidewall and on said drain side sidewall of said second transistor.

17) (currently amended) The method as described in Claim 16 wherein said first ~~oxide~~ transistor is a periphery transistor.

18) (original) The method as described in Claim 16 wherein said second transistor is a core transistor.

19) (original) The method as described in Claim 18 wherein said core transistor is a flash memory cell.

20) (currently amended) The method as described in Claim 16 wherein said first ~~oxide~~ layer comprises silicon oxide and silicon nitride.

21) (currently amended) The method as described in Claim 16 wherein said second ~~oxide~~ layer comprises nitride.

22) (original) The method as described in Claim 16 wherein said c) is a self aligned source etch.

23) (currently amended) The method as described in Claim 16 wherein said first ~~oxide~~ layer is thicker than said second ~~oxide~~ layer.